

Proudly Made in USA

ISO 9001:2008

Fusionbond® 372 Sales Sheet

PDS_FB372_1

FUSIONBOND® 372





Product Features:

- Halogen free; 3rd party independent tested
- Non-sagging gaps filled to 0.372 inch
- Superior impact and peel strength
- Little or no surface preparation
- Rapid room temperature cure
- 100% reactive
- Excellent environmental resistance

Product Description:

Hernon® Fusionbond® 372 is a highly thixotropic, two component, room temperature curing, 1:1 ratio, methacrylate adhesive system.

Fusionbond®372 is formulated to provide fixturing strength within 10 to 15 minutes. **This adhesive is Halogen free.** Fusionbond® 372 forms resilient bonds and maintains its strength over a wide range of temperatures.



Typical Properties (Uncured):

Property	Part A	Part B
Chemical Type	Methacrylate	Methacrylate
Appearance	White	Blue
Specific gravity	0.97	0.94
Viscosity at 25°C, cP	30,000 to 50,000	30,000 to 50,000
Mix ratio (by weight)	1	1
Flash Point	See MSDS	See MSDS

Typical Curing Performance:

Property	Value
Working time, minutes	≥ 15
Fixture time, as received steel, mins.	10 to 12

Typical Cured Performance:

Shear Strength, ASTM D1002 Gritblasted lap-shear specimens

Property	Cure at 22°C	Value
Hardness		50-60
Shear Str Steel	24 hours	>2000 psi
Shear Str Aluminum	24 hours	>2000 psi
Impact Str, Stl after 48 hours	ASTM D4812	>50 Joules
Impact Str, Alum after 48 hours	ASTM D4812	>50 Joules
T-peel Str, Alum	24 hour	15-25 PIW
Dielectric Strength	ASTM D149	78.5 V/mil
Dielectric Constant	ASTM D150	1.5Mhz
Dissipation factor	ASTM D150	0.006

Bondable Substrates:

- ABS
- Acrylics (PMMA)
- Aluminum
- Brass
- Ceramics
- Copper
- Epoxy
- Fiberglass
- Gel Coats

- Steel & Stainless Steel
- Phenolics
- Polycarbonate and blends
- Polyurethanes
- PPO and PPO blends
- PVC & Vinyls
- Rim urethane
- Rubber
- And many more

Fusionbond® 372 Manufacturing Applications:

- Marine
- Automotive
- Replaces Welding
- Sporting Equipment
- Aerospace
- Replaces Rivets
- Golf Clubs
- Military Equipment
- No halogens make 372 ideal for electronic assemblies